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-	9	((boundary adj2 scan or test adj access adj port or tap) same (id or identification or code)) same voltage) same pin\$2	USPAT	2002/07/02 15:25
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VLSI Circuits, 2000. Digest of Technical Papers. 2000 Symposium on , 2000

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Electronics Manufacturing Technology Symposium, 1996., Nineteenth IEEE/CP

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Advanced Packaging, IEEE Transactions on [see also Components, Packaging Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on Volume: 22 Issue: 3 , Aug. 1999

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Polymeric Electronics Packaging, 1997. Proceedings., The First IEEE Internatio Symposium on , 1997

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Wang, T.-C.; Long, J.; Kwong, P.

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